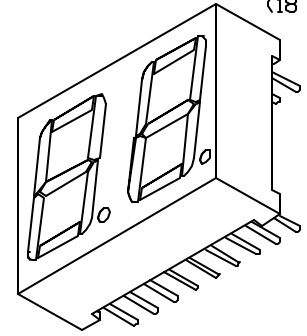
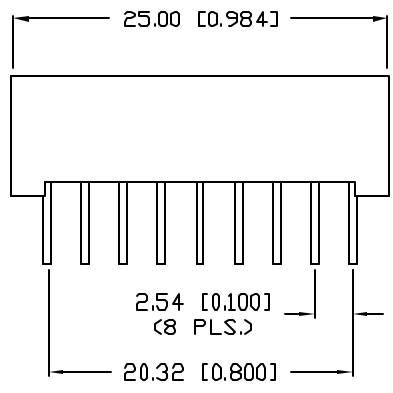
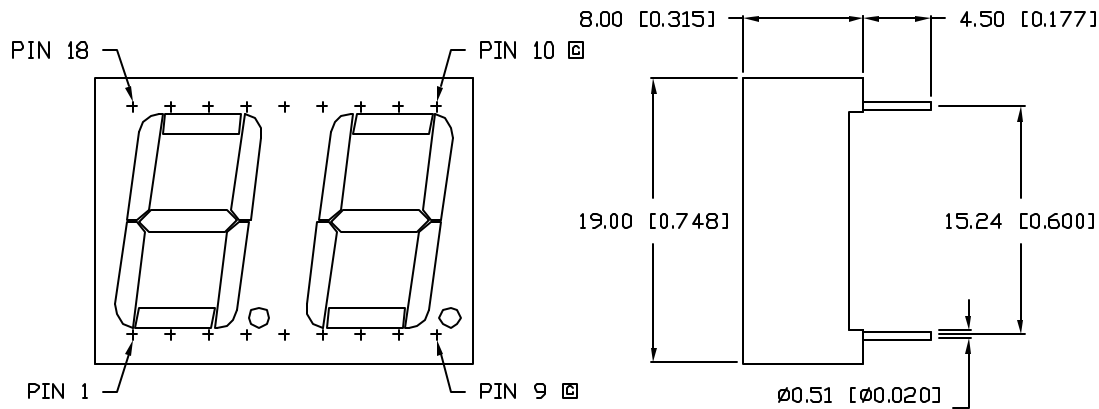
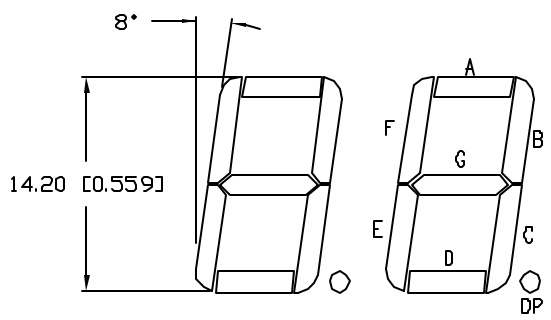


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CHARACTER DETAIL



DIG.1

DIG.2

\*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), X.X=±0.5 (±0.020), X.XX=±0.25 (±0.010), X.XXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030), MIN= <sup>+0.00</sup> <sub>-0.00</sub> DECIMAL PRECISION, MAX= <sup>+0.00</sup> <sub>-0.00</sub> DECIMAL PRECISION

PART NUMBER		REV.
LDD-A515R1		D
REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #10188. & 10113.	6.24.96
B	E.C.N. #10BRDR.	2.12.99
C	E.C.N. #10732. & REDRAWN IN 3D.	5.2.01
D	E.C.N. #11148.	4.26.07

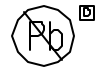
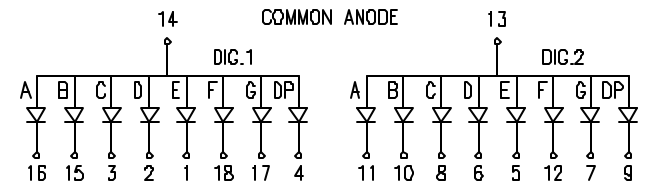
ELECTRO-OPTICAL CHARACTERISTICS  $T_A=25^{\circ}\text{C}$   $I_f=10\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		700		nm	
FORWARD VOLTAGE		2.0	2.5	V <sub>f</sub>	
REVERSE VOLTAGE	5.0			V <sub>r</sub>	I <sub>r</sub> =100μA
AXIAL INTENSITY		1400		μcd	I <sub>f</sub> =10mA
EMITTED COLOR:	RED				
FACE COLOR:	GRAY				
SEGMENT COLOR:	MILKY WHITE DIFFUSED				

LIMITS OF SAFE OPERATION AT 25°C PER CHIP

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	150	mA
STEADY CURRENT	25	mA
POWER DISSIPATION	120	mW
DERATE FROM 25°C	-1.2	mW/°C
OPERATING, STORAGE TEMP.	-40 TO +85	°C
SOLDERING TEMP.	+260	°C
2.0mm FROM BODY	3 SEC. MAX	

\* t<10μs



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REV.	PART NUMBER
D	LDD-A515R1

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0.56" SEVEN SEGMENT, DUAL DIGIT DISPLAY,  
 700nm RED CHIPS, GRAY FACE WITH WHITE SEGMENTS,  
 COMMON ANODE, RIGHT DECIMAL PLACE.

**RELIABILITY NOTE**  
 OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY:	CHECKED BY:	APPROVED BY:	DATE:
JC			4.8.96
			PAGE: 1 OF 1
			SCALE: N/A